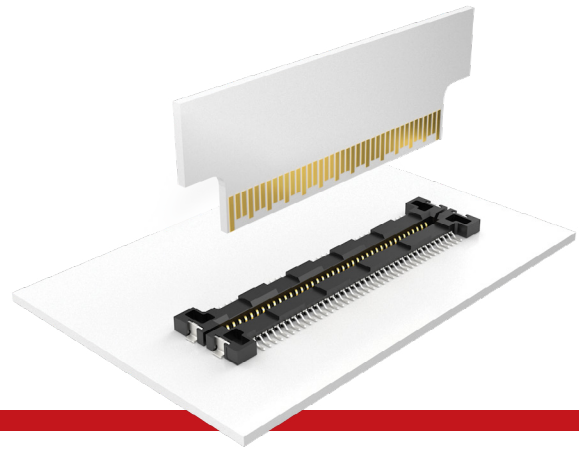


# HIGH-SPEED THROUGH BOARD SOCKET

(1.00 mm) .0394" PITCH • SAL1 SERIES

14  
G b p s



## SAL1

### Card Mates:

(1.60 mm) .062" or  
(2.36 mm) .093" card

## SPECIFICATIONS

### Insulator Material:

Black LCP

### Contact Material:

BeCu

### Plating:

Au or Sn over 50  $\mu$ " (1.27  $\mu$ m) Ni

### Operating Temp Range:

-55 °C to +125 °C

### Current Rating:

2.9 A per pin  
(2 adjacent pins powered)

### Voltage Rating:

215 VAC/304 VDC

## PROCESSING

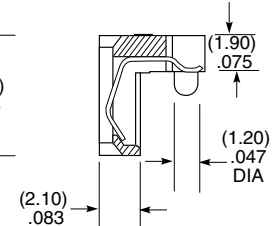
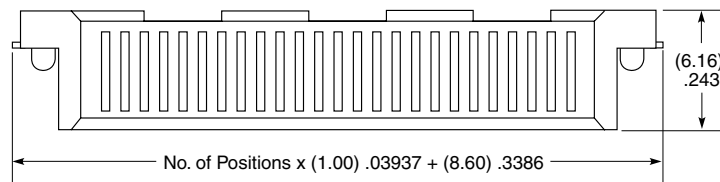
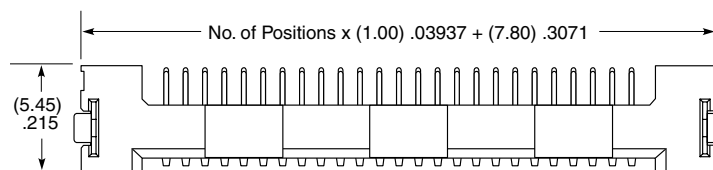
### Lead-Free Solderable:

Yes

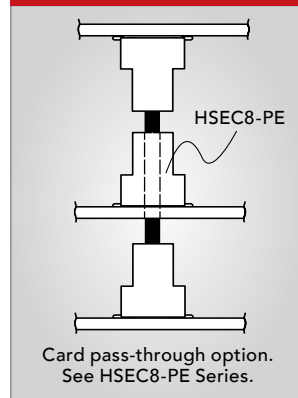
### SMT Lead Coplanarity:

(0.10 mm) .004" max

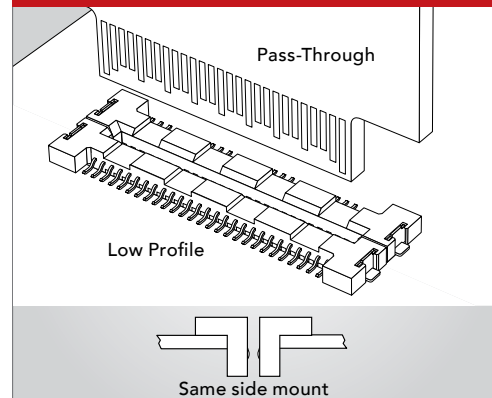
SAL1	-	1	NO. OF POSITIONS	-	01	PLATING OPTION	-	S	-	A	-	OPTION
			-20, -27, -30, -40			-S = 30 $\mu$ " (0.76 $\mu$ m) Gold on contact, Matte tin on tail						-TR = Tape & Reel  -FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks)



## OTHER SOLUTION



## APPLICATIONS



### Notes:

While optimized for 50  $\Omega$  applications, this connector with alternative signal/ground patterns may also perform well in certain 75  $\Omega$  applications..

Some lengths, styles and options are non-standard, non-returnable.

View complete specifications at: [samtec.com?SAL1](http://samtec.com?SAL1)

[samtec.com/EdgeCard](http://samtec.com/EdgeCard)

F-224 (Rev 09DEC24) WEB

Unless otherwise approved in writing by Samtec, all parts and components are designed and built according to Samtec's specifications which are subject to change without notice.